

■ Application

Control equipment controlling heat excessively generated within the chamber in the semiconductor manufacturing process, and maintaining temperature by selecting from low to high temperature.

■ Applied fields

Etching, CVD

■ General Features

- ▶ Heat energy storage system
- ▶ Dynamic temperature coordination
- ▶ Energy savings
- ▶ Long MTBF
- ▶ Multi channel is used with one refrigeration system
- ▶ Quick response time, minimum variation
- ▶ Small sized footprint

■ Utility Requirements

Item	Specification	
	Single	Duale
Dimension	450(W)×890(D)×1490(H)	450(W)×890(D)×1490(H)
Temperature Range	1CH : -20°C ~ +80°C	2CH : -20°C ~ +80°C
Cooling Capacity	1CH : 5000 watts at 10 °C	2CH : 3000 watts at 10 °C
Coolant Flow Rate	30LPM	30LPM
Coolant Type	FC-3283	FC-3283
Electrical Spec	208V, 3P, 4W, 30A	208V, 3P, 4W, 60A
Temperature Accuracy	±0.1 °C	±0.1 °C

